

CALL FOR NOMINATIONS

2006 IEEE Components, Packaging & Manufacturing Technology Award

Submitted by Dennis Olsen, Ph.D.

IEEE's Components, Packaging & Manufacturing Technology Award is presented for meritorious contributions to the advancement of components, electronic packaging or manufacturing technologies.

The Award is sponsored by the CPMT Society. The recipient of the award receives a bronze medal, certificate, and cash honorarium.

This IEEE CPMT Award was established in 2002. The technical field for this award includes all aspects of device and systems packaging including packaging of microelectronics, optoelectronics, RF and wireless and micro-electro-mechanical systems (MEMS).

This award may be presented to an individual or a team of not more than three. It is administered by the Technical Field Awards Council of the IEEE Awards Board.

The nomination deadline is **31 January 2006**. For nomination forms, visit the IEEE Awards Web Site:

www.ieee.org/awards

or please contact:

IEEE Awards Activities
445 Hoes Lane,
Piscataway, NJ, USA
08855-1331
Tel: +1-732-562-3844
Email: awards@ieee.org

CPMT Society Awards for Year 2005

Nomination Form

(Due date: January 31, 2006)

We invite your nomination of fellow practitioners for the many CPMT Society awards to be presented this year. For nomination forms and descriptions of all the available awards, please see the September CPMT NEWSLETTER, or download the nomination forms from the Awards website:

www.cpmt.org/awards

Nominations are due by **January 31, 2005**. For more information, please contact Awards Chair Rao Bonda, Freescale Semiconductor, at r.bonda@ieee.org.